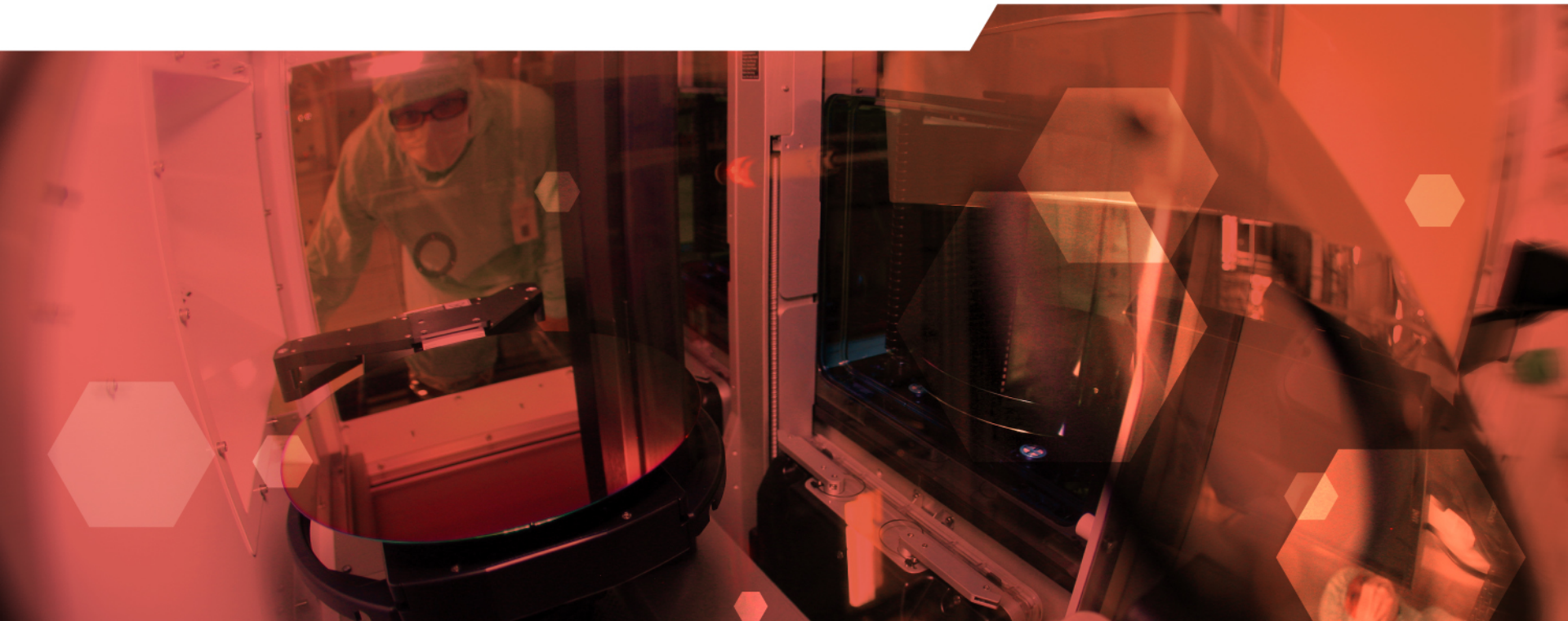


# North America TC Chapter Physical Interfaces & Carriers (PIC) Global Technical Committee

## Liaison Report

April 2018

V3.1



# Meeting Information

- Last meeting
  - Wednesday, April 11, 2018 at the SEMI Standards NA Spring Meetings
    - SEMI Headquarters, Milpitas, CA
- Next meeting
  - Wednesday, July 11, 2018 at the SEMICON West Standards Meetings
    - Marriot Marquis, San Francisco, CA

<http://www.semi.org/en/standards-events>

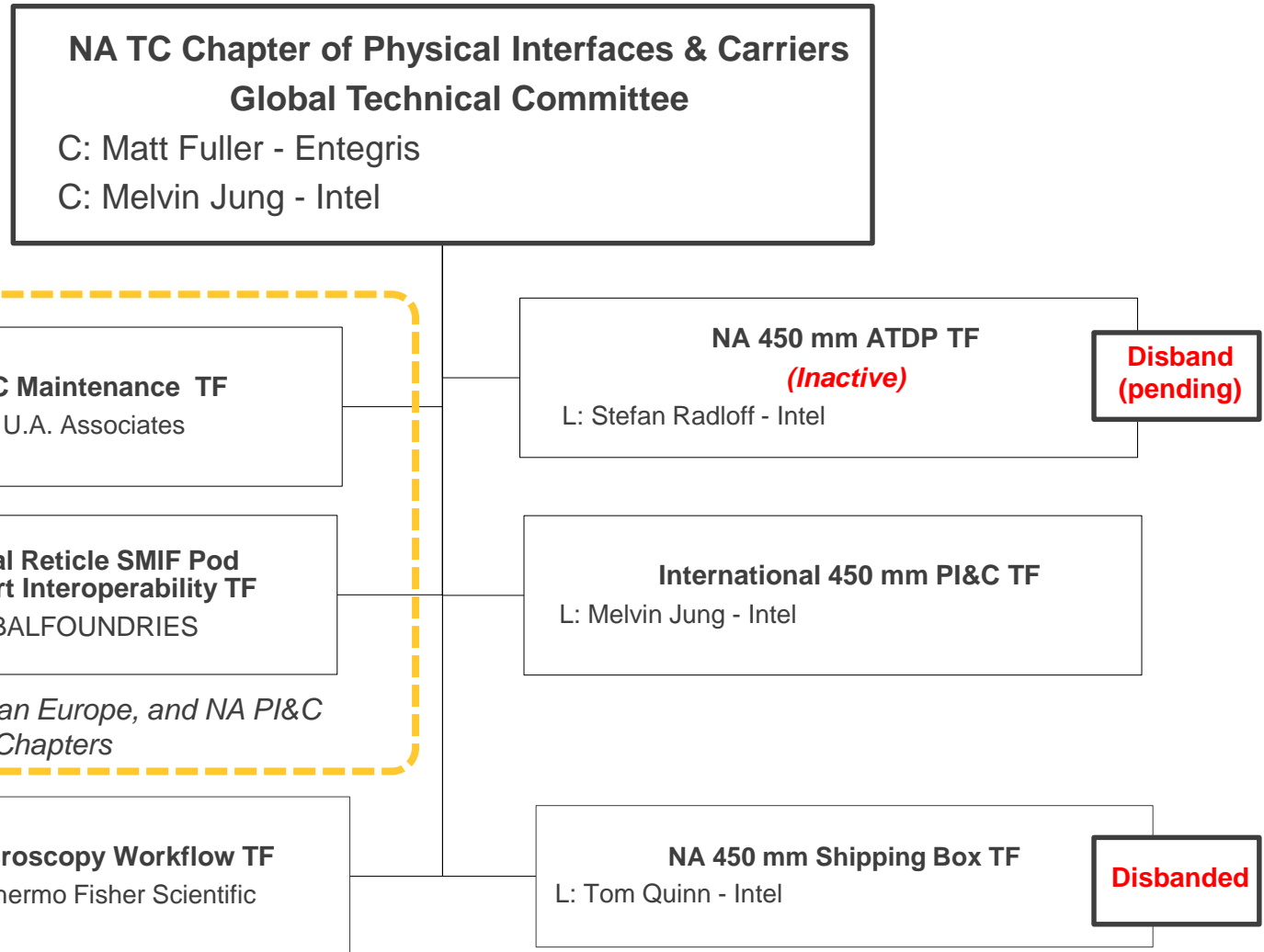
# Leadership

- Committee Cochairs
  - Matt Fuller (Entegris)
  - Melvin Jung (Intel)
- Technical Architect
  - Open

# Committee Structure Changes

<i>Previous TF/SC/CFG Name</i>	<i>New TF/SC/CFG Name or Status Change</i>
NA 450 mm Shipping Box Task Force	Disband – Approved by the NA Spring TC Chapter meeting on April 10, 2018

# Organization Chart



# Task Force Highlights [1/3]

- Electron Microscopy Workflow TF
  - Work ongoing
    - 6311: New Standard, Specification for TEM lamella carrier used in Electron Microscopy Workflows
  - Ongoing TF teleconference meetings (please contact Laura Nguyen or Troy Morrison, troy.morrison@fei.com, to be added to distribution list)
    - May 10, 2018 (7:00-8:00 PDT)
  - Minutes posted at: <https://sites.google.com/a/semi.org/electron-microscopy-workflow-task-force/>
    - Will move to [connected@semi](mailto:connected@semi) sites (TBD)
- Global PIC Maintenance TF
  - Did not meet during Spring meetings 2018
  - Will review Standards coming up for Five-year review at next meeting, SEMICON West 2018

# Task Force Highlights [2/3]

- NA 450 mm ATDP TF (Inactive)
  - Currently no activity in the NA Region
  - Most of the work has been done in JA 450 mm ATDP TF under the Japan Assembly & Packaging committee
    - The initiating region for Standards developed by the ATDP must be clearly confirmed before NA 450 mm ATDP TF can decide to move forward with disbandment.
  - Japan ATDP TF did not object to NA's proposal to disband NA 450 mm ATDP TF
  - NA PIC TC Chapter is also requesting that Japan ATDP TF agree to disband
    - Japan ATDP TF does not plan to disband at this time

# Task Force Highlights [3/3]

- International Reticle SMIF Pod and Load Port Task Force
  - Activities under this task force have been completed
  - Disbandment of the NA International Reticle SMIF Pod and Load Port TF was approved at the NA Spring TC Chapter meeting on April 5, 2017.
  - Request to EU PIC TC Chapter to agree on disbanding as well



# Nonconforming Titles

## (See PM Appendix 4)

- SEMI E152-0214, Mechanical Specification of EUV Pod for 150 mm EUVL Reticles
- SEMI E154-0814, Mechanical Interface Specification for 450 mm Load Port
  - Originated in NA
  - Last reviewed in Japan
- SEMI E158-0314, Mechanical Specification for Fab Wafer Carrier Used to Transport and Store 450 mm Wafers (450 FOUP) and Kinematic Coupling
- SEMI E159-0314, Mechanical Specification for Multi Application Carrier (MAC) Used to Transport and Ship 450 mm Wafers

# Five-Year Review

Designation	Standard Title	Action By	Assigned to
*SEMI E152-0214	Mechanical Specification of EUV Pod for 150 mm EUVL Reticles*	Fall 2018	Global PIC Maintenance TF
*SEMI E158-0314	Mechanical Specification for Fab Wafer Carrier Used to Transport and Store 450 mm Wafers (450 FOUP) and Kinematic Coupling*	Fall 2018	Global PIC Maintenance TF
*SEMI E159-0314	Mechanical Specification for Multi Application Carrier (MAC) Used to Transport and Ship 450 mm Wafers*	Fall 2018	Global PIC Maintenance TF

*\* Nonconforming title needs to be addressed in addition to Five-Year review*

# Thank you!

For more information or to participate in any  
NA PIC activities, please contact:

Laura Nguyen  
SEMI Headquarters, Milpitas, CA  
[Inguyen@semi.org](mailto:Inguyen@semi.org)